A B C D E F G H

## PCB MANUFACTURING SPECIFICATIONS "Altium Templates"

## **SPECIFICATIONS**

NOTE #	NOTE
1	ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK
2	SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION
3	ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN ROHS ASSEMBLY. ROHS LOGO SHALL BE MARKED IN SILKSCREEN INK NEAR BY THE SUPPLIER.
4	COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS
5	ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-CONDUCTIVE, PERMANENT INK.
6	MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM_NOTES" BY THE TEXT "PLACE MARKINGS HERE".
7	MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS OTHERWISE NOTED ONTO THE LAYER "PCBM_NOTES"
8	SUPPLIER SHALL CHECK PCBM_NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS
9	MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES

## Layer Stack Legend Thickness Dielectric Material Type Material Layer Gerber Top Overlay Legend GTO Top Solder Solder Mask Top Surface Finish Lead-Free 0.02mm Surface Finish CF-004 Top Layer 0.04mm Signal **GTL** Core Core-043 Dielectric 1.50mm CF-004 0.04mm Signal GBL **Bottom Layer** Bottom Surface Finish 0.02mm Surface Finish Surface Material Bottom Solder 0.03mm SM-001 Solder Mask GBS **Bottom Overlay** Legend GBO

Total thickness: 1.66mm

## **SPECIFICATIONS**

JI LUII IUATIUNU	
LENGHT	80.00mm
WIDTH	75.00mm
LAYERS	2
MATERIAL	FR-4
MATERIAL MIN TG	130-140
TRACK WIDTH/CLEARANCE	8 mils / 8 mils
THICKNESS	1.6mm
COPPER THICKNESS	35um (1oz)
SOLDERMASK	YES, TOP AND BOTTOM
SOLDERMASK COLOR	RED
SILKSCREEN	YES, TOP AND BOTTOM
SILKSCREEN COLOR	WHITE
SURFACE FINISH	HASL LEAD FREE
GOLD FINGERS	NO
CHAMFERING	NO
IMPEDANCE CONTROL	NO
HALF-CUT/CASTELLATED HOLES	NO
BURIED/BLIND VIAS	NO
VIAS FILLED WITH RESIN	NO
CARBON MASK	NO
COUNTERSINKS/COUNTERBORES	NO
Z-AXIS MILLING	NO
PEELABLE SOLDERMASK	NO

NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE

miti		Author:	CONFIDENTIAL
Title: Altium Templates		Approved:	My Company
Size: A3		<b>Edited:</b> 25/08/2020	Address Line 1
Size: A3 Unit: mm Prj: Altium T	emplates	Variant: [No Variations]	
Date: 25/08/2020 22:57	Sheet 1 of 3	<b>SW version:</b> 20.1.14.287	Address Line 3
<b>Git Hash:</b> 8dce3f0d473152	Address Line 4		
	. \ \	3 . \	

YOUR LOGO HERE

Н

A B C D E F G



